

<b>INFORMATION DISCLOSURE CITATION PTO-1449</b>	Atty. Docket No. 950637B	Serial No. Div. of. 08/769,529 <sup>09/1393722</sup>
	Applicant(s): T. Akamatsu et al	
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### U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
<u>A</u>	AA	5,859,470	Ellerson et al	1/99			
<u>B</u>	AB	5,007,163	Pope et al	4/91			
<u>C</u>	AC	5,391,514	Gall et al	2/95			
<u>D</u>	AD	5,376,584	Agarwala	12/94			
	AE						

### FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Translation (Yes or No)
<u>A</u>	AF	64-28931	1/89	JAPAN	
<u>B</u>	AG	306634	12/98	JAPAN	
	AH				
	AI				
	AJ				

### OTHER DOCUMENTS

<u>A</u>	AK	Zegun Mei, <u>Low Temperature Solders</u> , Hewlett-Packard Journal; p. 91, August 1996.
<u>B</u>	AL	IBM Technical Disclosure Bulletin, Vol. 32, No. 4A, September 1989, pg. 273-274.
Examiner <u>John</u>		Date Considered 9-22-00